



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON) max}	Package	I _D T _A = +25°C
	1.0Ω @ V _{GS} = -4.5V		-600mA
-20V	1.5Ω @ $V_{GS} = -2.5V$	V4 DEN4040.0	-500mA
	2.0Ω @ V _{GS} = -1.8V	X1-DFN1212-3	-400mA
	3.0Ω @ V _{GS} = -1.5V		-250mA

Description

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions

Features

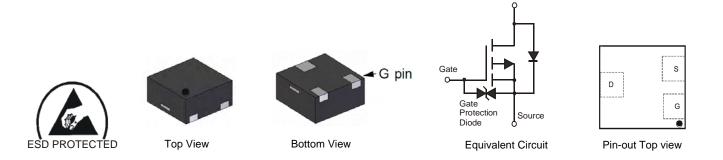
- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)}, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
 - Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X1-DFN1212-3
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208

Drain

- Terminal Connections: See Diagram
- Weight: 0.005 grams (approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP21D5UFD-7	X1-DFN1212-3	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



KP2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Y = 2011) M = Month (ex: 9 = September)

Date Code Key

Year	201	1	2012		2013	20	14	2015		2016		2017
Code	Υ		Z		Α		3	С		D		E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage		V_{DSS}	-20	V
Gate-Source Voltage		V_{GSS}	±8	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	I _D	-600 -500	mA	
Continuous Drain Current (Note 6) V _{GS} = -1.8V	I _D	-400 -300	mA	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I_{DM}	-2	Α	
Maximum Body Diode continuous Current	I _S	-800	mA	

Thermal Characteristics

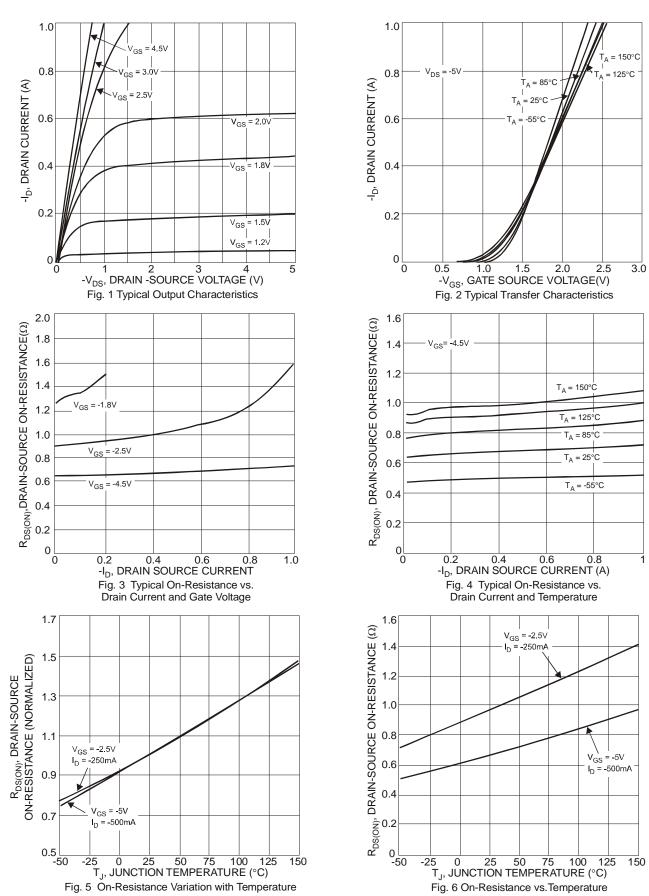
Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 5)		P_{D}	0.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{\theta JA}$	280	°C/W
Total Power Dissipation (Note 6)		P _D	0.8	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	140	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V$, $I_D = -1mA$		
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-80 -100	nA	$V_{DS} = -4.5V, V_{GS} = 0V$ $V_{DS} = -20V, V_{GS} = 0V$		
Gate-Source Leakage	I _{GSS}		_	±10.0	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 7)				l .				
Gate Threshold Voltage	V _{GS(th)}	-0.5	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		
		_	0.7	1.0		$V_{GS} = -4.5V, I_{D} = -100mA$		
		_	0.9	1.5		$V_{GS} = -2.5V, I_{D} = -80mA$		
Static Drain-Source On-Resistance	R _{DS (ON)}	_	1.2	2.0	Ω	$V_{GS} = -1.8V, I_D = -40mA$		
	= 5 (5.1)		1.5	3.0		$V_{GS} = -1.5V, I_D = -30mA$		
		_	5	_		$V_{GS} = -1.2V, I_D = -1mA$		
Forward Transfer Admittance	Y _{fs}	_	0.7	_	S	$V_{DS} = -3V, I_{D} = -100mA$		
Diode Forward Voltage	V _{SD}	_	-0.75	-1.2	V	$V_{GS} = 0V$, $I_{S} = -330mA$,		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	C _{iss}	_	46.1	_		101/1/		
Output Capacitance	Coss	_	7.2	_	pF	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1.0MHz		
Reverse Transfer Capacitance	C _{rss}	_	4.9	_		I = 1.0WII IZ		
Total Gate Charge V _{GS} = -4.5V	Qg	_	0.5	_				
Total Gate Charge V _{GS} = -8V	Q_g	_	0.8	_	nC	101/1 050 4		
Gate-Source Charge	Q _{gs}	_	0.1	_	nc nc	$V_{DS} = -10V, I_{D} = -250mA$		
Gate-Drain Charge	Q_{gd}	_	0.1	_				
Turn-On Delay Time	t _{D(on)}		8.5	_		., ., .,		
Turn-On Rise Time	t _r		4.3	_	1	$V_{DD} = -3V, V_{GS} = -2.5V,$		
Turn-Off Delay Time	t _{D(off)}		20.2	_	ns	$R_L = 300\Omega, R_G = 25\Omega,$		
Turn-Off Fall Time	t _f	_	19.2	_		$I_D = -100 \text{mA}$		

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- Device mounted on FR-4 substrate PC board, 2oz copper, with 1 inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.







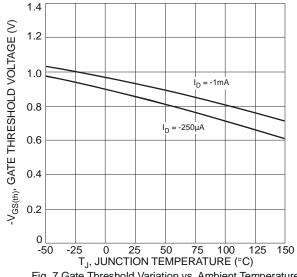
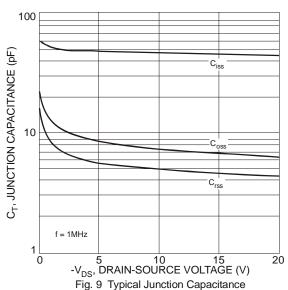
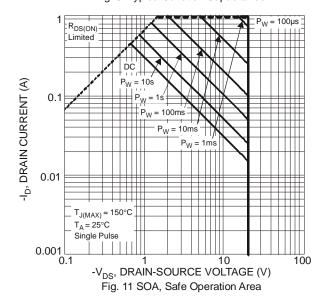
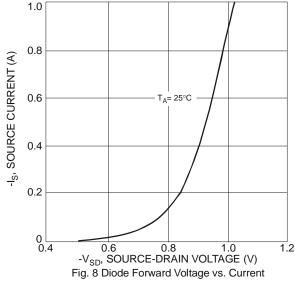


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







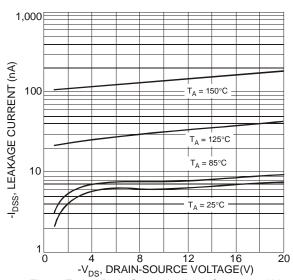
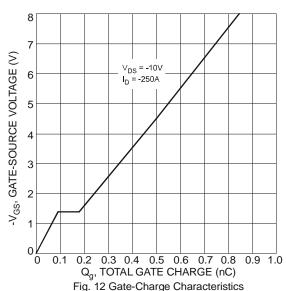


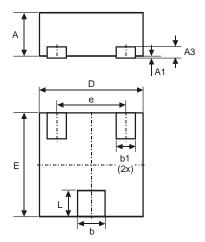
Fig. 10 Typical Drain-Source Leakage Current vs. Voltage





Package Outline Dimensions

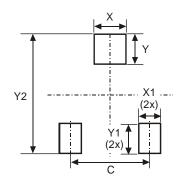
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



X1-DFN1212-3							
Dim	Min	Max	Тур				
Α	0.47	0.53	0.50				
A1	0	0.05	0.02				
A3	1	•	0.13				
b	0.27	0.37	0.32				
b1	0.17	0.27	0.22				
ם	1.15	1.25	1.20				
Е	1.15	1.25	1.20				
е	•	•	0.80				
Ĺ	0.25	0.35	0.30				
All Di	All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.80
Х	0.42
X1	0.32
Y	0.50
Y1	0.50
Y2	1.50



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